Sicrys™ Copper Digital Conductive Inks

Product name	Solvent				Ink								
	Solvent	Viscosity @ 25°C (cP)	Surface tension (dyne/cm)	Evap. Rate @ 25°C (nBuAc=1)	Solids (metal content)	Cu^0 in Cu nano-particles	Viscosity @ 25°C (cP)	Surface tension* (dyne/cm)	Open time (min) (jetting temp.,°C)	Resistivity (μΩcm) (thermal sintering, °C, min, Argon)	Substrate adhesion tested***	Compatible printheads	Storage
IC25EG-1	EG	17.1	48.0	0.01	25%	>90%	32	47	5 min (35°C)	≤ 5 # ≤ 32 ## ≤ 90 (300, 30, Ar)	Kapton, PA, LCP, glass	KM1024 KM1024i Ricoh E3 DMC-11610 Air Brush	Room temperature Argon environment
IC50TM-8	TGME	6.2	36.4	<0.01	50%	>95%	32	34	20 min (40°C)	≤ 5 # ≤ 120 (300, 30, Ar)	Kapton, FR4, ITO, glass	KM1024 KM1024i Ricoh E3 DMC-11610 Air Brush	Room temperature Argon environment

Solvents: EG - ethylene glycol, TGME - triethylene glycol monomethyl ether.
Notes: * - Surface tension measured with Pendant Drop method; # - Laser sintering; ## - Photonic sintering;
*** - Adhesion depends on substrate, sintering conditions, substrate pretreatment and pattern thickness (tested according to ASTM-3359-09 or ISO-2409)

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